

E2791/E2791LF GR-1244 and GR-253-Core Stratum 3 Minature Surface Mount TCXO

ISSUE 2 : 13 JUNE 2005

Nominal Frequency, Fo

■ 20.0MHz

Supply Voltage

■ 3.3V ±5%

Input Current

■ ≤ 6mA

Output

Type : HCMOS
 Load : 15pF max
 Vol : ≤ 0.1 * Vs
 VoH : ≥ 0.9 * Vs

■ Duty Cycle @ 50%: 45% to 55%

■ Rise Time, 10% to 90%: <9ns

■ Fall Time, 90% to 10%:<9ns

Holdover Stability [±(F_{max}-F_{min}) /2.F_o]

■ Temperature, -20 to 70°C: ±0.28ppm

 Temperature, -20 to 70°C, inclusive of Supply Voltage, 3.3V ± 5% and Ageing 24 hours: ≤ ±0.32ppm

Free-Run Accuracy, incl,

■ Calibration @ 25°C, Temperature -20 to 70°C, Supply Voltage 3.3V ±5%, Load 15pF ±5%, Reflow Soldering and Ageing 20 years: < ±4.6ppm ref. to F_o

Phase Noise

■ 10Hz <u><</u> -85dBc/Hz

■ 100Hz ≤-110dBc/Hz

■ 1kHz <u><</u>-125dBc/Hz

■ ≥10kHz ≤-135dBc/Hz

Tri-state

■ Pad 8 open circuit or ≥0.6Vs : Output Enabled

■ Pad 8 \leq 0.2Vs : Output in Tri-state mode

 When in tri-state mode, the output is disabled but the oscillator and compensation circuit are still active (Current consumption ≤ 1mA).

Marking (laser)

- Manufacturers ID (RAKON)
- Manufacturers identifier (xx)
- Pad 1 / Static Sensitivity Identifier (△)
- Abbreviated Part Number (2791)
 Oscillator's Date of Manufacture (YW)



Note: Production parts will be marked in this format. Sample marking may vary.

Environmental Specification

- Storage Temperature Range: -55 to 125°C
- Vibration: IEC 60068-2-6Test Fc Procedure B4, 10-60Hz 1.5mm displacement, at 98.1 m/s², 30 minutes in each of three mutually perpendicular axes at 1 octave per minute.
- Shock: IEC 6006-2-27 Test Ea, 980m/s² acceleration for 6ms duration, 3 shocks in each direction along three mutually perpendicular axes.
- Solderability: MIL-STD-202, Method 208, Catergory 3.
- RoHS/Soldering: Parts with the suffix 'LF' on the part numbe are fully compliant with the European Union directive 2002/95/EC on the restriction of the use of certain hazardous substances in electrical and electronic equipment.
 Note: The RoHS compliant parts are suitable for assembly using both Lead-free solders (see Lead-free Reflow soldering profile) and Tin / Lead solders (see Tin / Lead Reflow solderin profile)



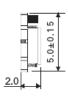
Outline in mm

Pin Connections

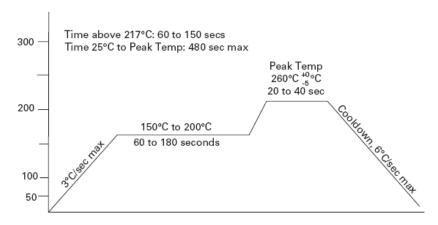
1.Do not connect 2.N/C 3.Do not connect 4.GND 5.Output 6.N/C 7.N/C

8.Tri-state Control* 9.Supply, +Vs 10.Do not connect, or connect to GND

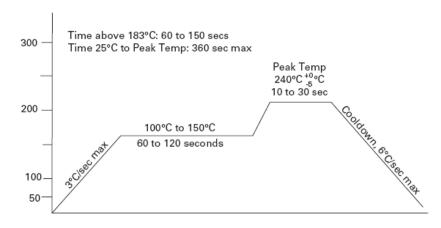
*Decouple with capacitor 100nF connected to GND



Lead Free Reflow Soldering Profile *



Tin / Lead Reflow Soldering Profile *



*Note:

These profiles were used during the qualification testing of the product and therefore represent worst case conditions. They are not recommended for use by the customer in the actual assembly of these parts